IPC ASSOCIATION CONNECTIN ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1					Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfc Information			
upplier Inform	ation								,						
Company name*			Company unique ID			ī	Unique ID Authority				Respon	Response Date*			
nsemi											2024-0	2024-05-16			
ontact Name		·	Title - Contact			1	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewa	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Represe	ntative*		Title - Representative			1	Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requeste	er Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	.]	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP12700ADNR2G Current M		Current Mode PWN	urrent Mode PWM Controller		2024-05-16 MY1		MY1	25.27		mg	Each			
	Process Informatio		amainal Daga	Allow	STD-020 MSI	Dating	Dools Droop	aga Dadu T	Commonsta	May Time at Dae	l. Tommon	Atuma Numah	per of Reflow Cyo	alac	
			Terminal Base Alloy J-STD CU Alloy 1		S I D-020 MSI	L Kanng	260	ak Process Body Temperat		me Max Time at Pea			ber of Reflow Cyc	cies	
•	n (Sn) - anneaieu		O Alloy	1			200		IC	30	seco	nus 3			
omments	ime at peak temperature	o during sole	doring is 10.2	A seconds											
	on regarding material co														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach	0.18	mg	Supplier	Silver (Ag)	7440-22-4		0.135	mg
			Supplier	Epoxy resins	129915-35-1		0.045	mg
Lead Frame	10.12	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0152	mg
			Supplier	Silicon (Si)	7440-21-3		0.0658	mg
			В	Nickel (Ni)	7440-02-0		0.3036	mg
			Supplier	Copper (Cu)	7440-50-8		9.7354	mg
Mold Compound-Black	12.98	mg		Epoxy Phenol Resin	proprietary data		1.3629	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.6171	mg
Plating	0.17	mg	Supplier	Palladium (Pd)	7440-05-3		0.0106	mg
			В	Nickel (Ni)	7440-02-0		0.1576	mg
			Supplier	Gold (Au)	7440-57-5		0.0018	mg
Wire Bond - Au	0.16	mg	Supplier	Gold (Au)	7440-57-5		0.16	mg